

a projection system for projecting the patterned beam onto a target portion of the substrate, characterised in that said method comprises the following steps:]

[a first placement step in which the] placing an object [is placed] at a first position on [the] a first object table;

[a] measuring [step in which] a displacement between the first position of the object and [the] a required position of the object [is determined];

[a] removing [step in which] the object [is released and removed] from the first object table;

[a] moving [step in which] the object and the first object table [are moved] relatively to each other by substantially the said displacement, in a direction substantially parallel to the plane of the table; and

[a second placement step in which] placing the object [is placed] at substantially the required position on the first object table.

2. (Amended) A method according to claim 1, wherein said measuring [step] comprises aligning a first mark on the object to a second, reference mark.

3. (Amended) A method according to claim 2, wherein said second mark is located on the [first or the second] one of the first object table and a second object table.

4. (Amended) A method according to claim 1 [or 2], wherein [the patterning means comprises] a mask is held by the first object table.

5. (Amended) A method according to claim [4] 2, wherein said second mark is located on [the] one of a mask [or the] and a substrate.

A1 6. (Amended) A method according to claim 1, wherein said measuring [step] is accomplished using imaging means to determine the displacement between the first position of the object and the required position of the object.

7. (Amended) A method according to [any of the proceeding claims] claim 1, wherein said measuring [step] comprises processing information about the first position of the object, together with information regarding the required position of the object[, in calculation means,] to determine said displacement.

11. (Amended) A method of positioning a substrate at a required position on a substrate table, [characterised in that] said method [comprises the following steps] comprising:

A2 [a first placement step in which] placing the substrate [is placed] at a first position on the table;

[a] measuring [step in which] a displacement between the first position of the substrate and [the] a required position of the substrate [is determined];

[a] removing [step in which] the substrate [is released and removed] from the table;

[a] moving [step in which] the substrate and the table [are moved] relatively to each other by substantially the said displacement, in a direction substantially parallel to the plane of the table; and

[a second placement step in which] placing the substrate [is placed] at substantially the required position on the table.

12. (Amended) A device manufacturing method comprising [the steps of]:

(a) providing a [second object] substrate table with a substrate which is at least partially covered by a layer of radiation-sensitive material;

(b) [using patterning means to endow the] patterning a projection beam [with] to produce a pattern in its cross-section; and

(c) projecting the patterned beam onto a target portion of the layer of radiation-sensitive material [, characterised in that, prior to step (c), the following actions are performed]:

[a first placement step in which] prior to said projecting, placing the substrate [is placed] at a first position on the [second object] substrate table;

[a] measuring [step in which] a displacement between the first position of the substrate and [the] a required position of the substrate [is determined];

[a] removing [step in which] the substrate [is released and removed] from the [second object] substrate table;

[a] moving [step in which] the substrate and the [second object] substrate table [are moved] relatively to each other by substantially the said displacement, in a direction substantially parallel to the plane of the second object table; and

[a second placement step in which] placing the substrate [is placed] at substantially the required position on the second object table.